MBN2400ES17D

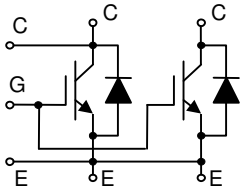
Preliminary SPEC.

Silicon N-channel IGBT

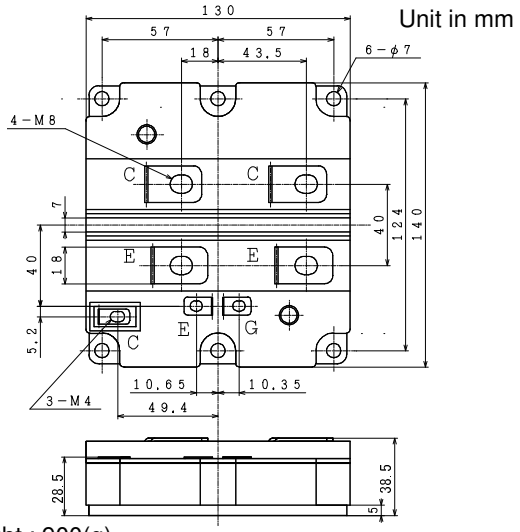
FEATURES

- High speed, low loss IGBT module.
- Low driving power due to low input capacitance MOS gate.
- Low noise due to ultra soft fast recovery diode.
- High reliability, high durability module.
- High thermal fatigue durability. (delta Tc=70°C, N>30,000cycles)
- Isolated heat sink (terminal to base).

CIRCUIT DIAGRAM



OUTLINE DRAWING



Weight : 900(g)

ABSOLUTE MAXIMUM RATINGS (Tc=25°C)

Item		Symbol	Unit	MBN2400ES17D
Collector Emitter Voltage		V_{CES}	V	1,700
Gate Emitter Voltage		V_{GES}	V	±20
Collector Current	DC	I_C	A	2,400
	1ms	I_{Cp}		4,800
Forward Current	DC	I_F	A	2,400
	1ms	I_{FM}		4,800
Junction Temperature		T_j	°C	-40 ~ +125
Storage Temperature		T_{stg}	°C	-40 ~ +125
Isolation Voltage		V_{ISO}	V_{RMS}	4,000(AC 1 minute)
Screw Torque	Terminals (M4/M8)	-	N·m	2/10 (1)
	Mounting (M6)	-		6 (2)

Notes: (1) Recommended Value 1.8±0.2/9±1N·m (2) Recommended Value 5.5±0.5N·m

ELECTRICAL CHARACTERISTICS

Item		Symbol	Unit	Min.	Typ.	Max.	Test Conditions
Collector Emitter Cut-Off Current		I_{CES}	mA	-	-	10	V_{CE}=1,700V, V_{GE}=0V, Tj=25°C
				-	15	50	V_{CE}=1,700V, V_{GE}=0V, Tj=125°C
Gate Emitter Leakage Current		I_{GES}	nA	-500	-	+500	V_{GE}=±20V, V_{CE}=0V, Tj=25°C
Collector Emitter Saturation Voltage		$V_{CE(sat)}$	V	-	2.7	3.3	I_C=2,400A, V_{GE}=15V, Tj=125°C
Gate Emitter Threshold Voltage		$V_{GE(TO)}$	V	5.0	6.5	8.0	V_{CE}=10V, I_C=240mA, Tj=25°C
Input Capacitance		C_{ies}	nF	-	220	-	V_{CE}=10V, V_{GE}=0V, f=100kHz, Tj=25°C
Internal Gate Resistance		Rg(int)	Ω	-	0.8	-	V_{CE}=10V, V_{GE}=0V, f=100kHz, Tj=25°C
Switching Times	Rise Time	t_r	μs	-	0.9	1.8	V_{CC}=900V, Ic=2400A
	Turn On Time	t_{on}		-	1.4	2.8	L=65nH
	Fall Time	t_f		-	0.3	0.6	R_G= 1.5Ω, Cge=220nF (3)
	Turn Off Time	t_{off}		-	1.8	3.6	V_{GE}=±15V, Tj=125°C
Peak Forward Voltage Drop		V_{FM}	V	-	2.1	2.5	IF=2400A, V_{GE}=0V, Tj=125°C
Reverse Recovery Time		t_{rr}	μs	-	0.7	1.4	V_{CC}=900V, IF=2400A, L=65nH Tj=125°C
Turn On Loss		$E_{on(10\%)}$	J/P	-	0.6	0.9	V_{CC}=900V, Ic= IF=2,400A, L=65nH
Turn Off Loss		$E_{off(10\%)}$	J/P	-	1.0	1.5	R_G= 1.5Ω, Cge=220nF (3)
Reverse Recovery Loss		$E_{rr(10\%)}$	J/P	-	0.5	0.8	V_{GE}=±15V, Tj=125°C
Stray inductance module		L_{SCE}	nH	-	15	-	
Thermal Impedance	IGBT	Rth(j-c)	K/W	-	-	0.011	Junction to case
	FWD	Rth(j-c)		-	-	0.017	
Contact Thermal Impedance		Rth(c-f)	K/W	-	0.008	-	Case to fin

Notes : (3) R_G and C_{GE} value is the test condition's value for evaluation of the switching times, not recommended value. Please, determine the suitable R_G and C_{GE} value after the measurement of switching waveforms (overshoot voltage, etc.) with appliance mounted.

* Please contact our representatives at order.
* For improvement, specifications are subject to change without notice.
* For actual application, please confirm this spec sheet is the newest revision.

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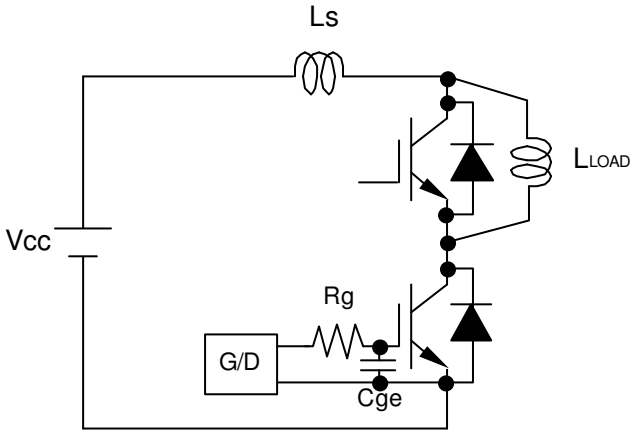
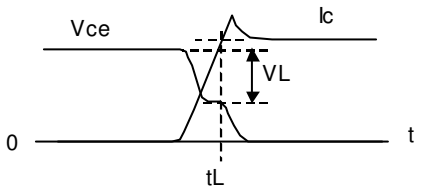
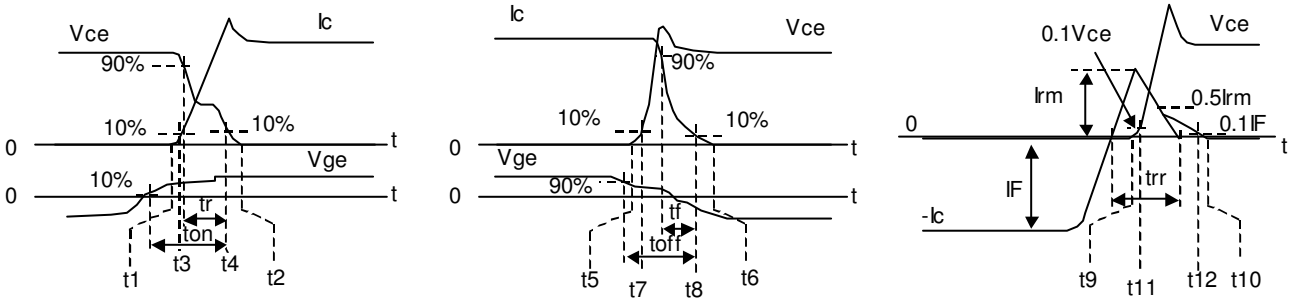


Fig.1 Switching test circuit



$$Ls = \frac{VL}{\left(\frac{dIc}{dt}\right)_{t=tL}}$$

Fig.2 Definition of Ls



$$Eon(10\%) = \int_{t3}^{t4} Ic \cdot Vce\, dt \qquad Eoff(10\%) = \int_{t7}^{t8} Ic \cdot Vce\, dt \qquad Err(10\%) = \int_{t11}^{t12} IF \cdot Vce\, dt$$

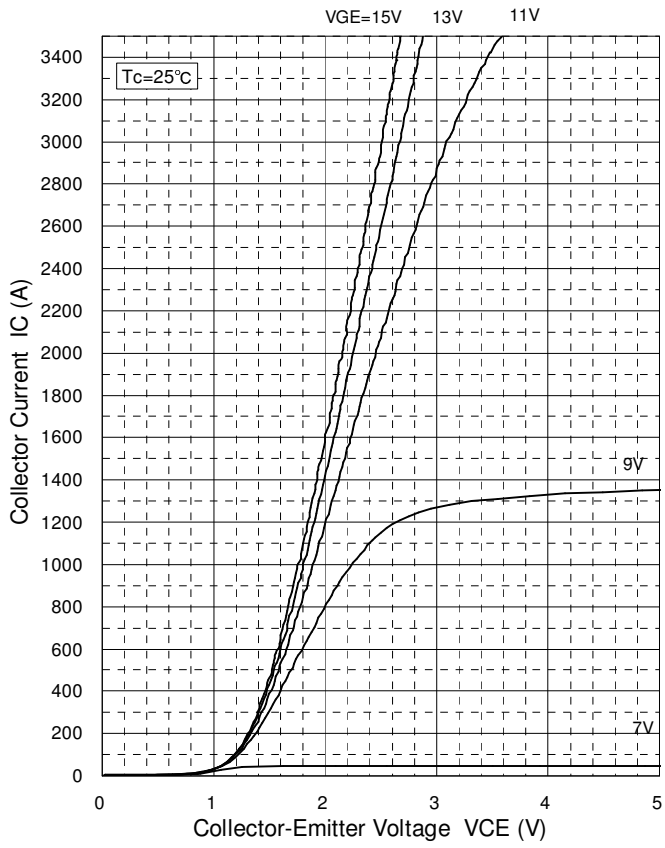
$$Eon(Full) = \int_{t1}^{t2} Ic \cdot Vce\, dt \qquad Eoff(Full) = \int_{t5}^{t6} Ic \cdot Vce\, dt \qquad Err(Full) = \int_{t9}^{t10} IF \cdot Vce\, dt$$

Fig.3 Definition of switching loss

CHARACTERISTICS CURVE

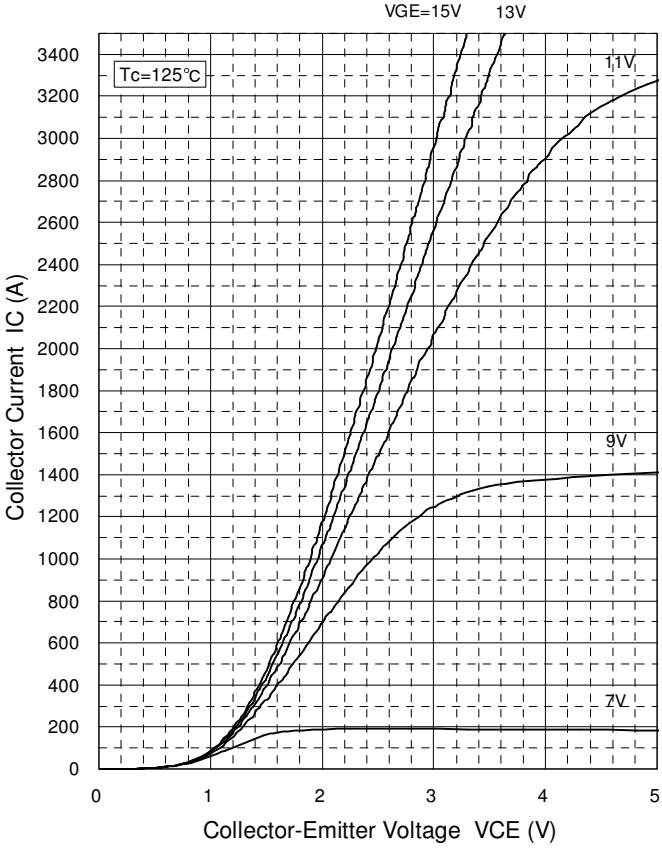
STATIC CHARACTERISTICS

TYPICAL



Collector Current vs.Collector to Emitter Voltage

TYPICAL



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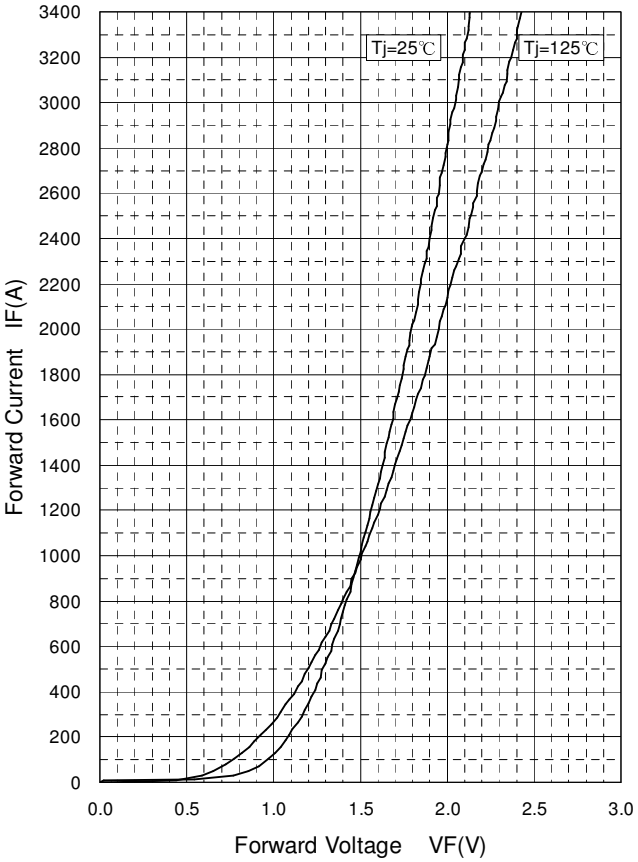

Forward Voltage of free-wheeling diode

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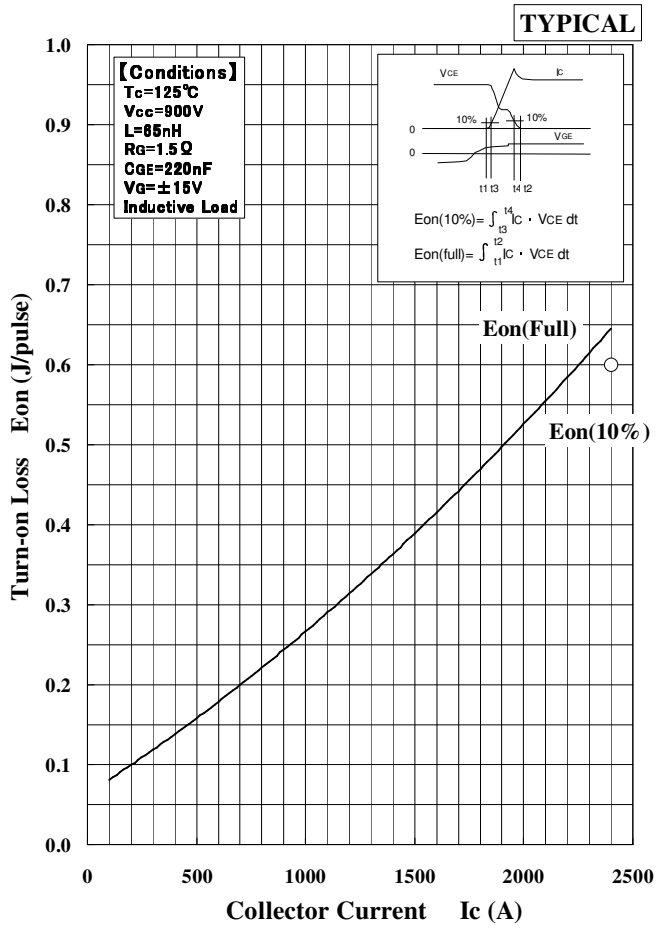
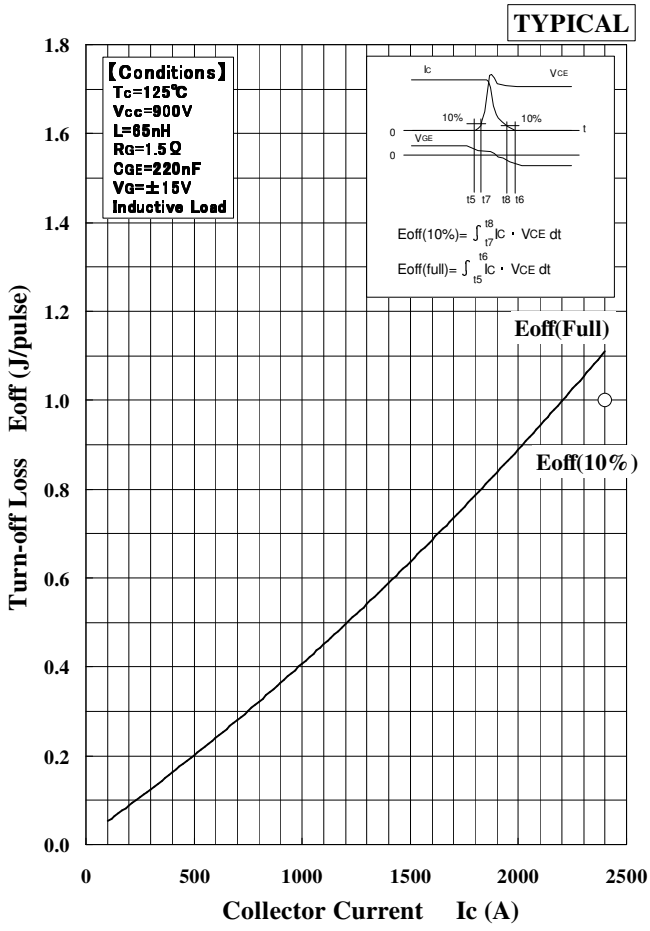
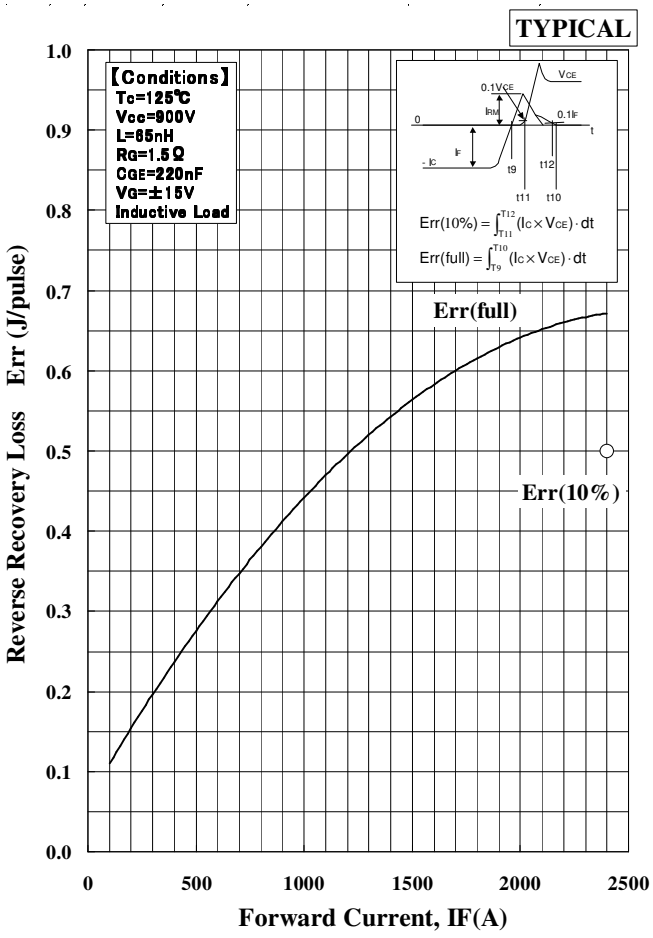
DEPENDENCE OF CURRENT



Turn-on Loss vs. Collector Current



Turn-off Loss vs. Collector Current



Recovery Loss vs. Collector Current

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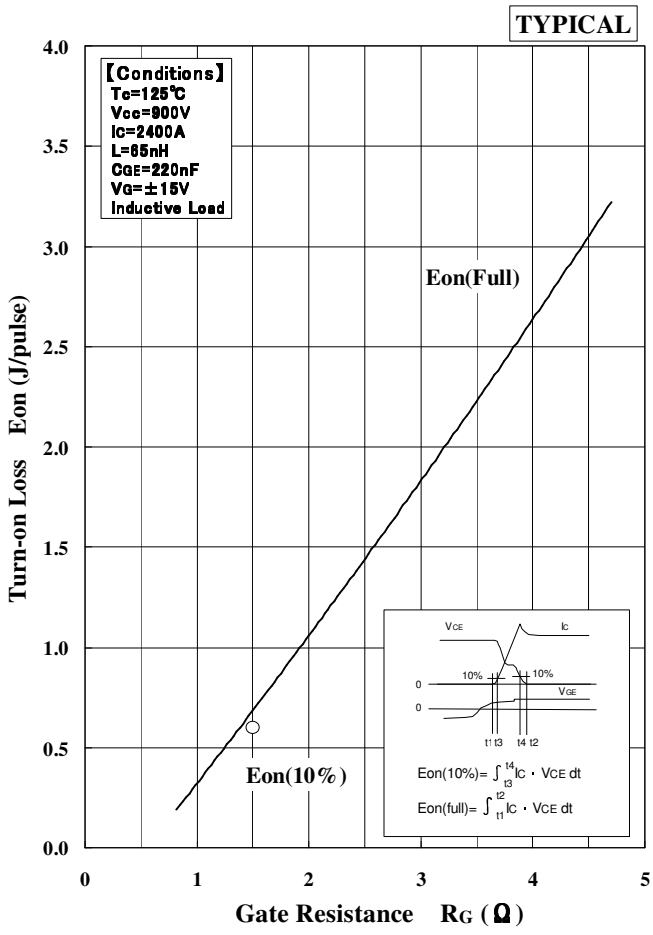
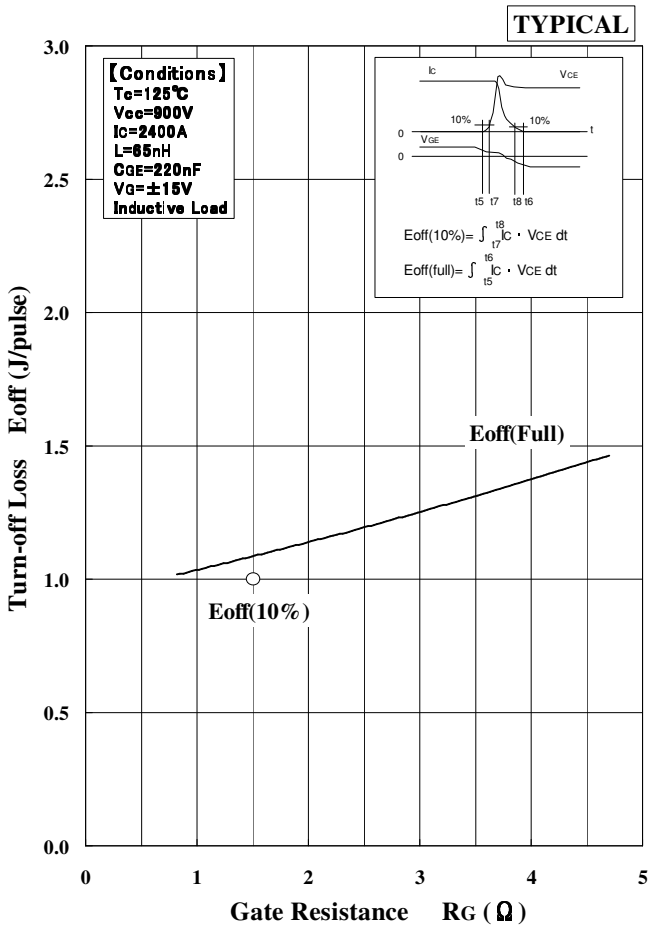
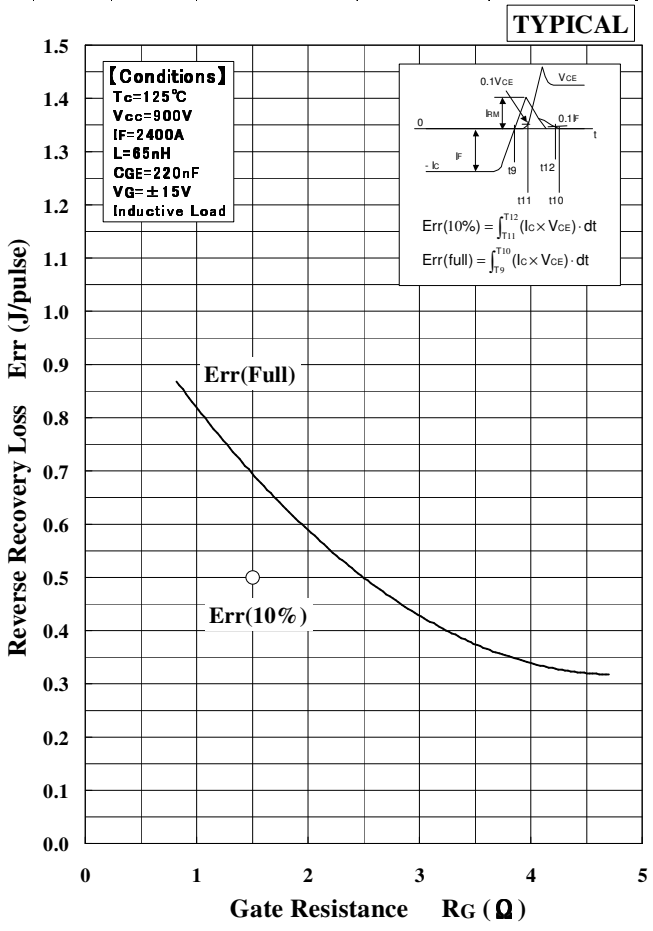
DEPENDENCE OF RG



Turn-on Loss vs. Gate Resistance



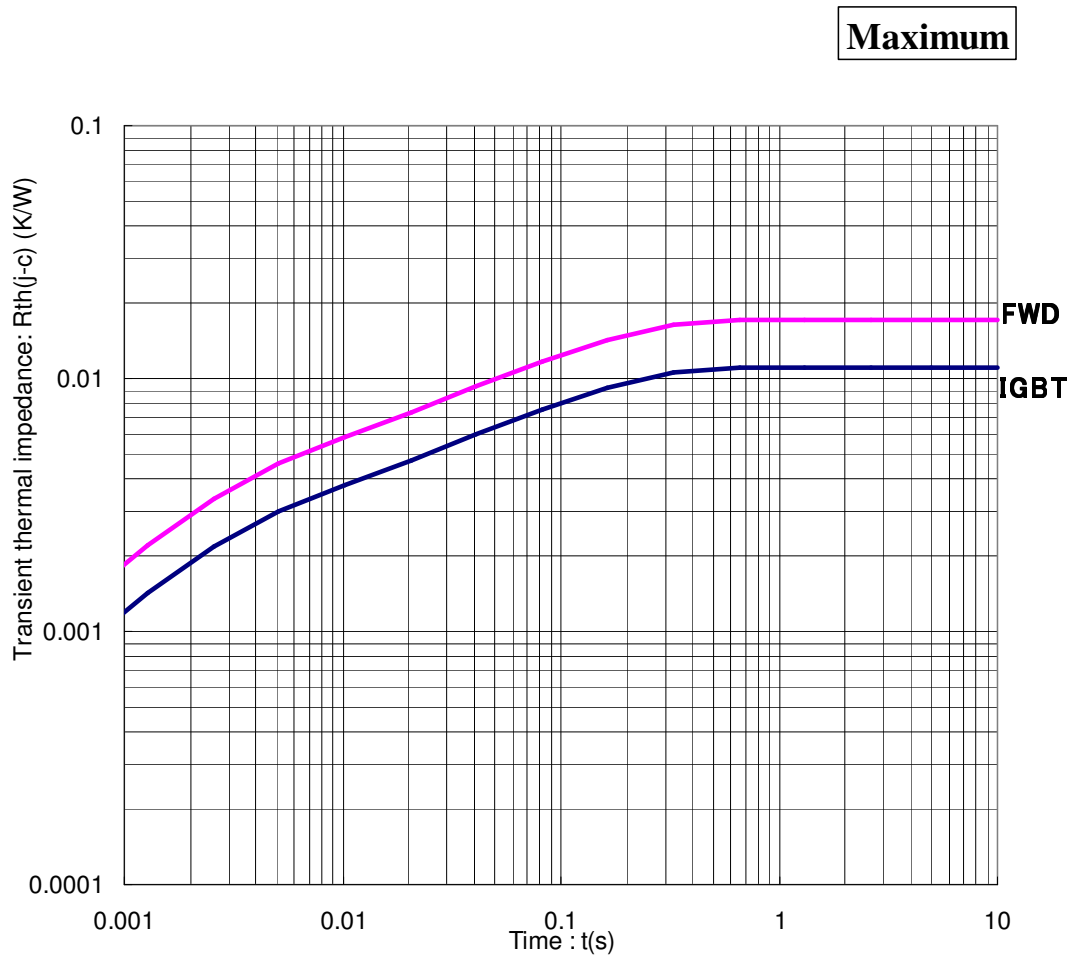
Turn-off Loss vs. Gate Resistance



Recovery Loss vs. Gate Resistance

Thermal Impedance

TRANSIENT THERMAL IMPEDANCE



Transient Thermal Impedance Curve

Negative environmental impact material

Please note the following negative environmental impact materials are contained in the product in order to keep product characteristic and reliability level.

Material	Contained part
Lead (Pb) and its compounds	Solder
Arsenic and its compounds	Si chip

HITACHI POWER SEMICONDUCTORS

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